

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB60R099P7	**Issued**	24. February 2022
MA#	MA005699643		
Package	PG-TO263-3-2	**Weight***	1561.47 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.092	0.45	0.45	4542	4542
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.47	19.50	194705	194958
wire	non noble metal	aluminium	7429-90-5	3.301	0.21	0.21	2114	2114
encapsulation	inorganic material	zincoxide	1314-13-2	6.833	0.44		4376	
	miscellaneous	miscellaneous	-	27.330	1.75		17503	
	plastics	epoxy resin	-	102.489	6.56		65636	
	inorganic material	silicondioxide	60676-86-0	546.608	35.01	43.76	350059	437574
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6184	6184
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.103	0.01		66	
	noble metal	silver	7440-22-4	0.128	0.01		82	
	non noble metal	lead	7439-92-1	4.905	0.31	0.33	3141	3289
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.07	35.12	350736	351192
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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